PHASE SHIFT RESONANT CONTROLLER

FEATURES

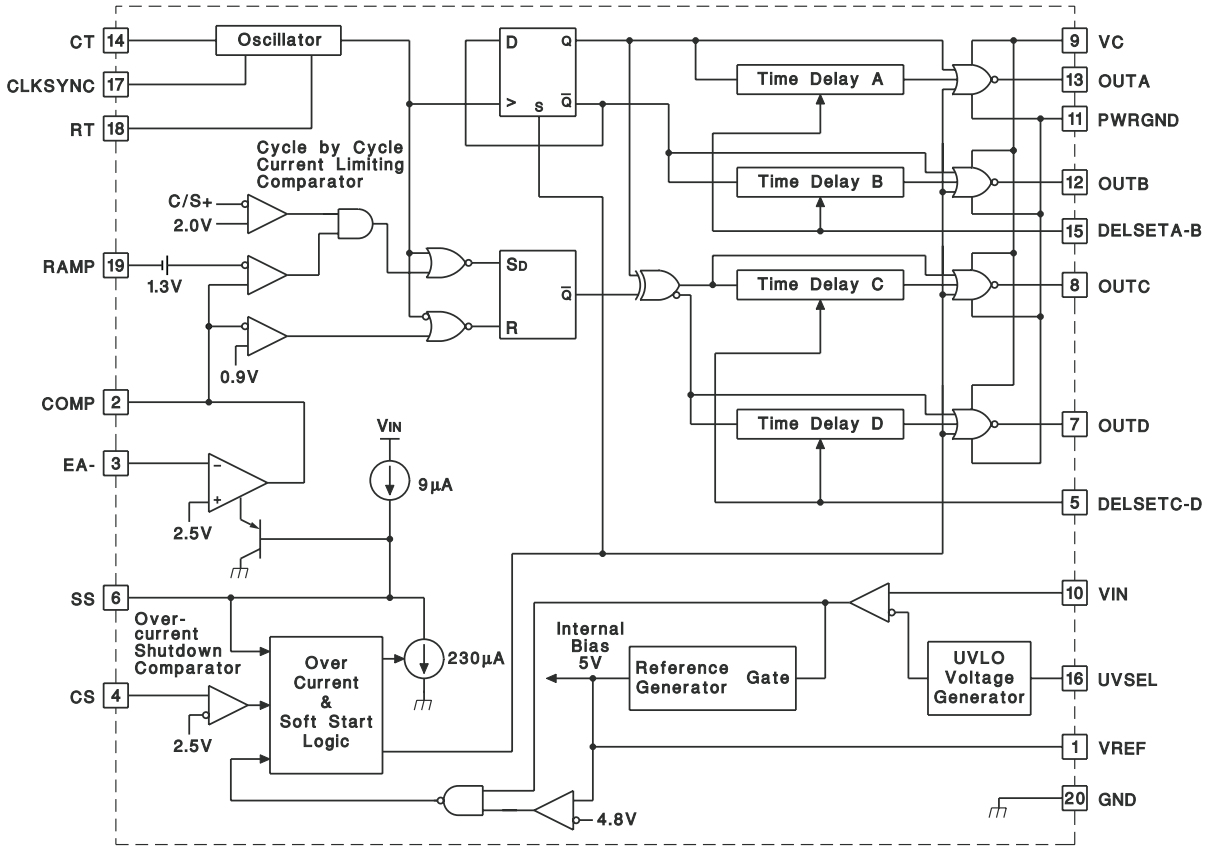
- **Programmable Output Turn On Delay; Zero Delay Available**
- **Compatible with Voltage Mode or Current Mode Topologies**
- **Practical Operation at Switching Frequencies to 300 kHz**
- **10-MHz Error Amplifier**
- **Pin Programmable Undervoltage Lockout**
- **Low Startup Current – 150 μA**
- **Soft Start Control**
- **Outputs Active Low During UVLO**

DESCRIPTION

The UC3879 controls a bridge power stage by phase shifting the switching of one half-bridge with respect to the other. This allows constant frequency pulse width modulation in combination with resonant, zero-voltage switching for high efficiency performance. The UC3879 can be configured to provide control in either voltage mode or current mode operation, with overcurrent shutdown for fast fault protection.

Independently programmable time delays provide dead-time at the turn-on of each output stage, allowing time for each resonant switching interval.

BLOCK DIAGRAM



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

DESCRIPTION (CONTINUED)

With the oscillator capable of operating in excess of 600 kHz, overall output switching frequencies to 300 kHz are practical. In addition to the standard free running mode, with the CLKSYNC pin, the user may configure the UC3879 to accept an external clock synchronization signal. Alternatively, up to three units can be locked together with the operational frequency determined by the fastest device.

Protective features include an undervoltage lockout and overcurrent protection. Additional features include a 10-MHz error amplifier, a 5-V precision reference, and soft start. The UC3879 is available in 20 pin N, J, DW, and Q and 28 pin L packages.

ABSOLUTE MAXIMUM RATINGS(1)

PARAMETER	VALUE	UNIT
Supply voltage (VC, VIN)	20	V
Output current, source or sink, dc	20	mA
Output current, source, sink peak for 0.1 μs at max frequency of 300 kHz	100	
Analog inputs		
(Pins 1, 2, 3, 4, 5, 6, 14, 15, 17, 18, 19)	–0.3 to 5.3	V
(Pin 16)	–0.03 to VIN	
Analog outputs		
(Pins 7, 8, 12, 13)	–0.3 to V_C to 0.3	V
Storage temperature range	–65°C to 150°C	°C
Junction temperature	–55°C to 150°C	
Lead temperature (soldering, 10 sec)	300°C	

(1) Pin references are to 20-pin DIL and SOIC packages. All voltages are with respect to ground unless otherwise stated. Currents are positive into, negative out of the specified terminal.

THERMAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

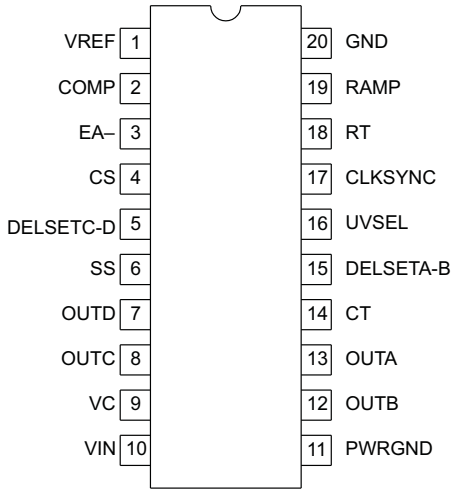
PACKAGE	θ_{JA}	θ_{JC}
J-20	70-85	28(1)
N-20	80(2)	35
DW-20 SOIC	45-95(2)	25
PLCC-20	43-75(2)	34
CLCC-20	N/A	5-8(2)(3)

(1) θ_{JC} data values stated were derived from MIL-STD-1835B. MIL-STD-1835B states "The baseline values shown are worst case (mean +2s) for a 60 x 60 mil microcircuit device silicon die and aplicable for devices with die sizes up to 14400 square mils. For devices die sizes greater than 14400 square mils use the following values; dual-in-line, 11°C/W; flat pacl 10°C/W; pin grid array, 10°C/W".
(2) Specified θ_{JA} (junction-to-ambient) is for devices mounted to 5-in^2 FR4 PC board with one ounce copper wire where noted. When resistance range is given, lower values are for 5-in^2 aluminum PC board. Test PWB was 0.062 in thick and typically used 0.635-mm trace widths for power packages and 1.3-mm trace widths for non-power packages with a 100 x 100 mil probe land area at the end of each trace.
(3) θ_{JC} estimated for backside of device, through the metalized thermal conduction pads.

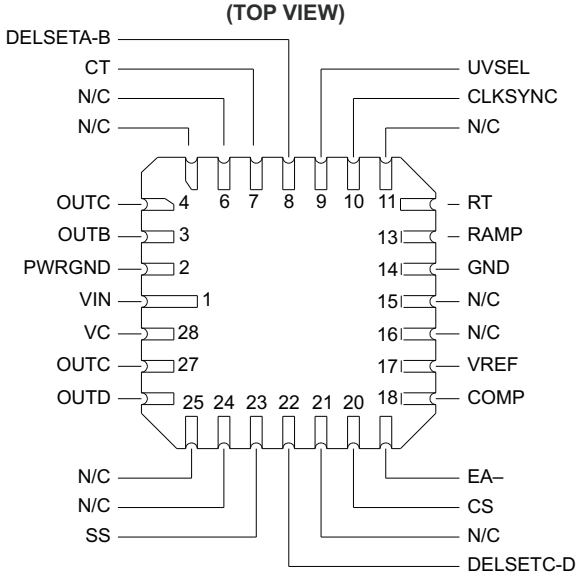
Product Selection Guide

	TEMPERATURE RANGE	AVAILABLE PACKAGES
UCC1879	–55°C to 125°C	J, L
UCC2879	–40°C to 85°C	N, DW, Q, J, L
UCC3879	0°C to 70°C	N, DW, Q

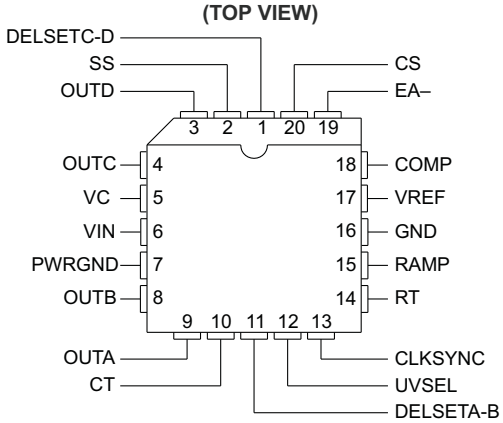
DIL-20, SOIC-2
J OR N PACKAGE, DW PACKAGE
(TOP VIEW)



CLCC-28
L PACKAGE
(TOP VIEW)



PLCC-20
Q PACKAGE
(TOP VIEW)



ELECTRICAL CHARACTERISTICS

Unless specified; VC = VIN = V_{UVSEL} = 12 V, CT = 470 pF, RT = 9.53k, $R_{DELSETA-B}$ = $R_{DELSEC-D}$ = 4.8k, $C_{DELSETA-B}$ = $C_{DELSETC-D}$ = 0.01 µF, T_A = T_J.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Undervoltage Lockout					
Start threshold	V_{UVSEL} = VIN	9	10.75	12.5	V
	V_{UVSEL} = Open	12.5	15.25	16.5	
UVLO hysteresis	V_{UVSEL} = VIN	1.15	1.75	2.15	
	V_{UVSEL} = Open	5.2	6	7.4	
Input bias, UVSEL pin	V_{UVSEL}= VIN = 8 V		30		µA
Supply Current					
I_{VIN} startup	VIN = V_{UVSEL} = 8 V, VC = 18 V, $I_{DELSETA-B}$ = $I_{DELSETC-D}$ = 0		150	600	µA
I_{VC} startup	VIN = V_{UVSEL} = 8 V, VC = 18 V, $I_{DELSETA-B}$ = $I_{DELSETC-D}$ = 0		10	100	
I_{VIN} operating	UC3879, UC2879		23	35	mA
	UC1879		23	36	
I_{VC} operating			4	8	
Voltage Reference					
Output voltage	T_J = 25°C	4.92	5	5.08	V
Line regulation	11 V < VIN < 18 V		1	10	mV
Load regulation	I_{VREF} = –10 mA		5	20	
Total variation	Line, Load, Temperature	4.875		5.125	V
Short circuit current	VREF = 0 V, T_J = 25°C		–60	–15	mA
Error Amplifier					
Error amplifier input voltage		2.4	2.5	2.6	V
Input bias current			0.6	3	µA
AVOL	1 V < VCOMP < 4 V	60	90		dB
PSRR	11 V < VIN < 18 V	85	100		
Output sink current	V_{COMP} = 1 V	1	2.5		mA
Output source current	V_{COMP} = 4 V		–1.3	–0.5	
Output voltage high	I_{COMP} = –0.5 mA	4	4.7	5	V
Output voltage low	I_{COMP} = 1 mA	0	0.5	1	
Slew rate	T_A = 25°C	6	11		V/µs

ELECTRICAL CHARACTERISTICS (continued)

Unless specified; VC = VIN = V_{UVSEL} = 12 V, CT = 470 pF, RT = 9.53k, $R_{DELSETA-B}$ = $R_{DELSEC-D}$ = 4.8k, $C_{DELSETA-B}$ = $C_{DELSETC-D}$ = 0.01 µF, T_A = T_J.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
PWM Comparator					
RAMP offset voltage	T_J = 25°C(1)	1.1	1.25	1.4	V
PWM phase shift, $T_{DELSETA-B}$, $T_{DELSETC-D}$ = 0(2)	V_{COMP}> $V_{RAMPpeak}$+ $V_{RAMPoffset}$	98%	99.7%	102%	
	V_{COMP} < Zero Phase Shift Voltage	0%	0.3%	2%	
Output skew, $T_{DELSETA-B}$, $T_{DELSETC-D}$ = 0(2)	V_{COMP}> $V_{RAMPpeak}$ + $V_{RAMPoffset}$		10		ns
	V_{COMP} < Zero Phase Shift Voltage		10		
Ramp to output delay, $T_{DELSETA-B}$ = 0, $T_{DELSETC-D}$ = 0	UC3879, UC2879		115	250	
	UC1879		115	300	
Oscillator					
Initial accuracy	T_A = 25°C	180	200	220	kHz
Voltage stability	11 V < VIN < 18 V		1	2	%
Total variation	Line, Temperature	160	200	240	kHz
CLKSYNC threshold		2.3	2.5	2.7	V
Clock out high		2.8	4		
Clock out low		0.5	1	1.5	
Clock out pulse width			400	600	ns
Ramp valley voltage			0.2	0.4	V
Ramp peak voltage		2.8	2.9	3.2	
Current Limit					
Input bias	V_{CS} = 3 V		2	10	µA
Threshold voltage		2.35	2.5	2.65	V
Delay to OUTA, B, C, D			160	300	ns
Cycle-by-Cycle Current Limit					
Input bias	V_{CS} = 2.2 V		2	10	µA
Threshold voltage		1.85	2	2.15	V
Delay to output zero phase			110	300	ns

(1) Ramp offset voltage has a temperature coefficient of about –4 mV/°C.

(2) Phase shift percentage (0% = 0 , 100% = 180) is defined as $\theta = \frac{200}{T}\phi\%$ where is the phase shift, and and T are defined in Figure 1. At 0% phase shift, is the output skew.

ELECTRICAL CHARACTERISTICS (continued)

Unless specified; VC = VIN = V_{UVSEL} = 12 V, CT = 470 pF, RT = 9.53k, $R_{DELSETA-B}$ = $R_{DELSEC-D}$ = 4.8k, $C_{DELSETA-B}$ = $C_{DELSETC-D}$ = 0.01 µF, T_A = T_J.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Soft Start/Reset Delay					
Charge current	V_{SS} = 0.5 V	–20	–9	–3	µA
Discharge current	V_{SS} = 1 V	120	230		µA
Restart threshold		4.3	4.7		V
Discharge level			300		mV
Output Drivers					
Output Low level	I_{OUT} = 10 mA		0.3	0.4	V
Output High level	I_{OUT} = –10 mA, Referenced to VC		2.2	3	V
Delay Set (3)					
Delay time (4)	$R_{DELSETA-B}$ = $R_{DELSETC-D}$ = 4.8k	250	370	520	ns
Delay time (4)	$R_{DELSETA-B}$ = $R_{DELSETC-D}$ = 1.9k	100	155	220	ns
Zero delay (5)	$V_{DELSETA-B}$ = $V_{DELSETC-D}$ = 5 V		5		ns

(3) Delay time can be programmed via resistors from the delay set pins to ground.

$$\text{Delay Time} = \left(0.89 \bullet 10^{-10} \bullet R_{DELAY}\right) \text{sec}$$

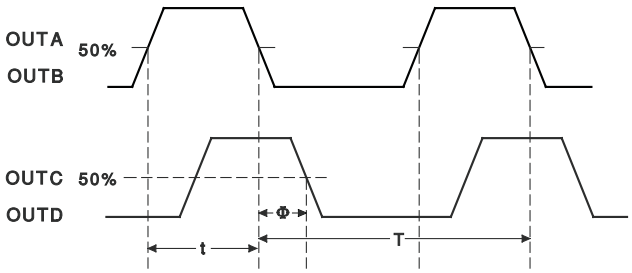
The recommended range for R_{DELAY} is 1.9 kΩ to 10 kΩ.

(4) Delay time is defined as:

$$\text{delay} = T \bullet \left(\frac{1}{2} - \text{duty cycle}\right)$$

where T is defined in Figure 1.

(5) The zero phase shift voltage is the voltage measured at COMP which forces zero phase shift. This condition corresponds to zero effective output power. Zero phase shift voltage has a temperature coefficient of about –2 mV/°C.



$$\text{DutyCycle} = \frac{t}{T}$$

$$\text{Period} = T$$

$$T_{DHL}(\text{A to C}) = T_{DHL}(\text{B to D}) =$$

Figure 1. Phase Shift, Output Skew and Delay Time Definitions

PIN DESCRIPTIONS

CLKSYNC (Bi-directional Clock and Synchronization): Used as an output, CLKSYNC provides a clock signal. As an input, this pin provides a synchronization point. Multiple UC3879s, each with their own local oscillator frequency, may be connected together by the CLKSYNC pin, and they will synchronize to the fastest oscillator. This pin may also be used to synchronize the UC3879 to an external clock, provided the frequency of the external signal is higher than the frequency of the local oscillator. CLKSYNC is internally connected to an emitter follower pull-up and a current source pull-down (300 μA typical). Therefore, an external resistor to GND can be used to improve the CLKSYNC pin's ability to drive capacitive loads.

COMP (Error Amplifier Output): This pin is the output of the gain stage for overall feedback control. Error amplifier output voltage levels below 0.9 V forces zero phase shift. Since the error amplifier has a relatively low current drive capability, the output may be overridden by driving it with a sufficiently low impedance source.

CT (Oscillator Frequency Set): After choosing RT to set the required upper end of the linear duty cycle range, the timing capacitor (CT) value is calculated to set the oscillator frequency as follows:

$$CT = \frac{Dlin}{1.08 \bullet RT \bullet f}$$

Connect the timing capacitor directly between CT and GND. Use a high quality ceramic capacitor with low ESL and ESR for best results. A minimum CT value of 200 pF insures good accuracy and less susceptibility to circuit layout parasitics. The oscillator and PWM are designed to provide practical operation to 600 kHz.

CS (Current Sense): This pin is the non-inverting input to the two current fault comparators whose references are set internally to fixed values of 2 V and 2.5 V. When the voltage at this pin exceeds 2 V, and the error amplifier output voltage exceeds the voltage on the ramp input, the phase shift limiting overcurrent comparator will limit the phase shifting on a cycle-by-cycle basis. When the voltage at this pin exceeds 2.5 V, the current fault latch is set, the outputs are forced OFF, and a soft start cycle is initiated. If a constant voltage above 2.5 V is applied to this pin the outputs are disabled and held low. When CS is brought below 2.5 V, the outputs will begin switching at 0 degrees phase shift before the SS pin begins to rise. This condition will not prematurely deliver power to the load.

DELSETA-B, DELSETC-D (Output Delay Control): The user programmed currents from these pins to GND set the turn on delay for the corresponding output pair. This delay is introduced between the turn off of one switch and the turn on of another in the same leg of the bridge to allow resonant switching to take place. Separate delays are provided for the two half-bridges to accommodate differences in the resonant capacitor charging currents.

EA– (Error Amplifier Inverting Input): This is normally connected to the voltage divider resistors which sense the power supply output voltage level. The loop compensation components are connected between this pin and COMP.

GND (Signal Ground): All voltages are measured with respect to GND. The timing capacitor on CT, and bypass capacitors on VREF and VIN should be connected directly to the ground plane near GND.

OUTA – OUTD (Outputs A-D): The outputs are 100-mA totem pole output drivers optimized to drive FET driver devices. The outputs operate as pairs with a nominal 50% duty cycle. The A-B pair is intended to drive one half-bridge in the external power stage and is synchronized to the clock waveform. The C-D pair drives the other half-bridge with switching phase shifted with respect to the A-B outputs.

PWRGND (Power Ground): VC should be bypassed with a ceramic capacitor from VC to the section of the ground plane that is connected to PWRGND. Any required bulk reservoir capacitor should be connected in parallel. PWRGND and GND should be connected at a single point near the chip to optimize noise rejection and minimize DC voltage drops.

RAMP (Voltage Ramp): This pin is the input to the PWM comparator. Connect it to CT for voltage mode control. For current mode control, connect RAMP to CS and also to the output of the current sense transformer circuit. Slope compensation can be achieved by injecting a portion of the ramp voltage from CT to RAMP.

PIN DESCRIPTIONS (continued)

RT (Clock/Sync Duty Cycle Set Pin): The UC3879 oscillator produces a sawtooth waveform. The rising edge is generated by connecting a resistor from RT to GND and a capacitor from CT to GND (see CT pin description). During the rising edge, the modulator has linear control of the duty cycle. The duty cycle jumps to 100% when the voltage on COMP exceeds the oscillator peak voltage. Selection of RT should be done first, based on the required upper end of the linear duty cycle range (D_{lin}) as follows:

$$RT = \frac{2.5}{10\,mA \bullet (1 - Dlin)}$$

Recommended values for RT range from 2.5 kΩ to 100 kΩ.

SS: Connect a capacitor between this pin and GND to set the soft start time. The voltage at SS will remain near zero volts as long as VIN is below the UVLO threshold. Soft start will be pulled up to about 4.8 V by an internal 9-μA current source when VIN and VREF become valid (assuming a non-fault condition). In the event of a current fault (CS voltage exceeding 2.5 V), soft start will be pulled to GND and then ramp to 4.8 V. If a fault occurs during the soft start cycle, the outputs will be immediately disabled and soft start must fully charge prior to resetting the fault latch. For paralleled controllers, the soft start pins may be paralleled to a single capacitor, but the charge currents will be additive.

UVSEL: Connecting this pin to VIN sets a turn on voltage of 10.75 V with 1.5 V of UVLO hysteresis. Leaving the pin open-circuited programs a turn on voltage of 15.25 V with 6 V of hysteresis.

VC (Output Switch Supply Voltage): This pin supplies power to the output drivers and their associated bias circuitry. The difference between the output high drive and VC is typically 2.1 V. This supply should be bypassed directly to PWRGND with a low ESR/ESL capacitor.

VIN (Primary Chip Supply Voltage): This pin supplies power to the logic and analog circuitry on the integrated circuit that is not directly associated with driving the output stages. Connect VIN to a stable source above 12 V for normal operation. To ensure proper functionality, the UC3879 is inactive until VIN exceeds the upper undervoltage lockout threshold. This pin should be bypassed directly to GND with a low ESR/ESL capacitor.

NOTE:

When VIN exceeds the UVLO threshold the supply current (I_{IN}) jumps from about 100 A to greater than 20 mA. If the UC3879 is not connected to a well bypassed supply, it may immediately enter the UVLO state again. Therefore, sufficient bypass capacity must be added to ensure reliable startup.

VREF: This pin provides an accurate 5 V voltage reference. It is internally short circuit current limited. VREF is disabled while VIN is below the UVLO threshold. The circuit is also disabled until VREF reaches approximately 4.75 V. For best results bypass VREF with a 0.1 μF, low ESR/ESL capacitor.

ADDITIONAL INFORMATION

Please refer to the following Unitrode publications for additional information. The following three topics are available in the Applications Handbook.

1. Application Note U-154, *The New UC3879 Phase- Shifted PWM Controller Simplifies the Design of Zero Voltage Transition Full-Bridge Converters*, by Laszlo Balogh.
2. Application Note U-136, *Phase Shifted, Zero Voltage Transition Design Considerations and the UC3875 PWM Controller*, by Bill Andreycak.
3. Design Note DN-63, *The Current-Doubler Rectifier: An Alternative Rectification Technique for Push-Pull and Bridge Converters,* by Laszlo Balogh.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
UC1879J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	-55 to 125		
UC1879J883B	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	-55 to 125		
UC2879DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2879DW	Samples
UC2879DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2879DW	Samples
UC2879DWTR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2879DW	Samples
UC2879DWTRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2879DW	Samples
UC2879J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	-40 to 85		
UC2879N	ACTIVE	PDIP	N	20	20	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UC2879N	Samples
UC2879NG4	ACTIVE	PDIP	N	20	20	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	UC2879N	Samples
UC3879DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3879DW	Samples
UC3879DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3879DW	Samples
UC3879DWTR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3879DW	Samples
UC3879DWTRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3879DW	Samples
UC3879J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	0 to 70		
UC3879N	ACTIVE	PDIP	N	20	20	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UC3879N	Samples
UC3879NG4	ACTIVE	PDIP	N	20	20	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UC3879N	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

OTHER QUALIFIED VERSIONS OF UC1879, UC3879 :

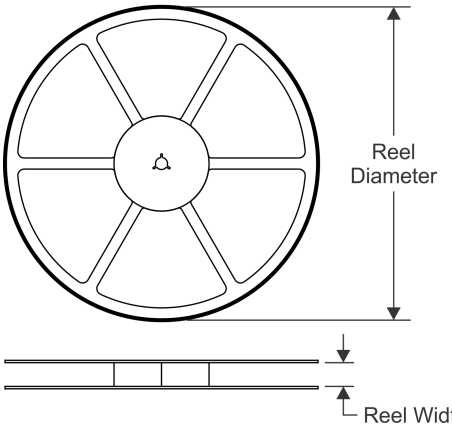
- Catalog: UC3879
- Military: UC1879

NOTE: Qualified Version Definitions:

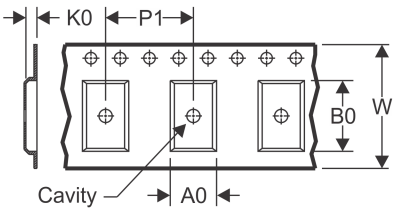
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

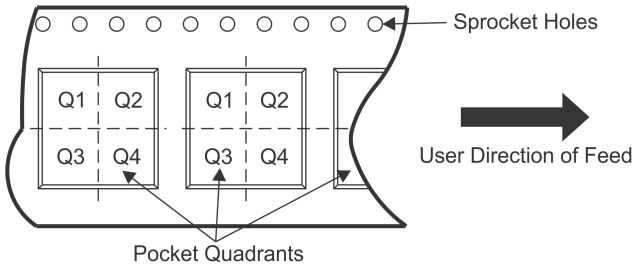


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

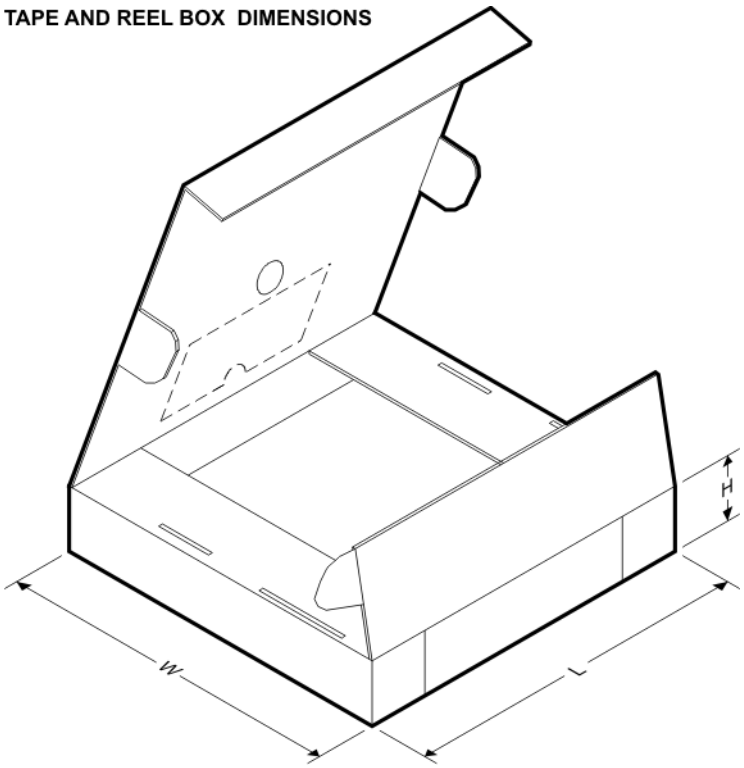
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC3879DWTR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



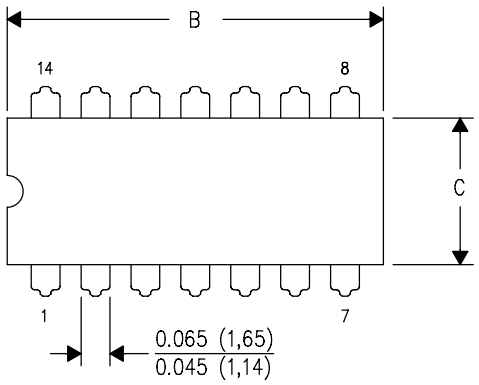
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC3879DWTR	SOIC	DW	20	2000	367.0	367.0	45.0

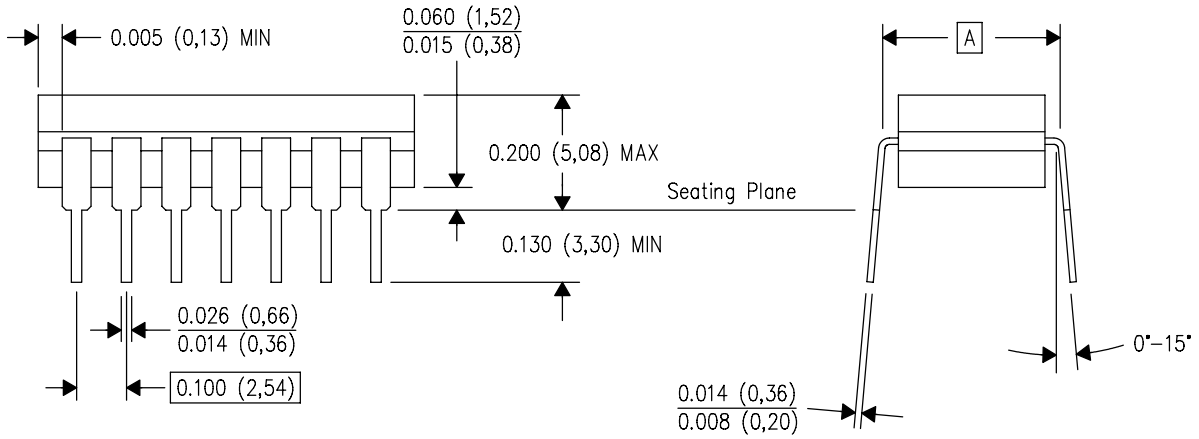
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



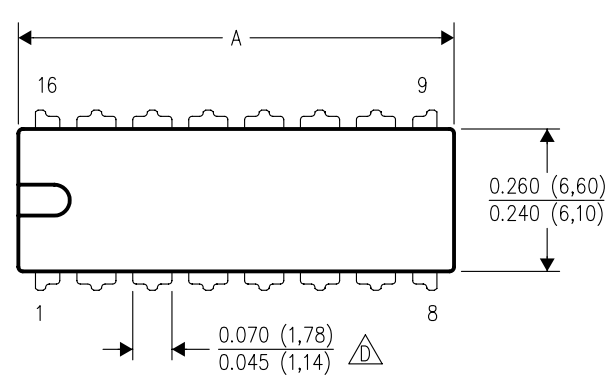
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

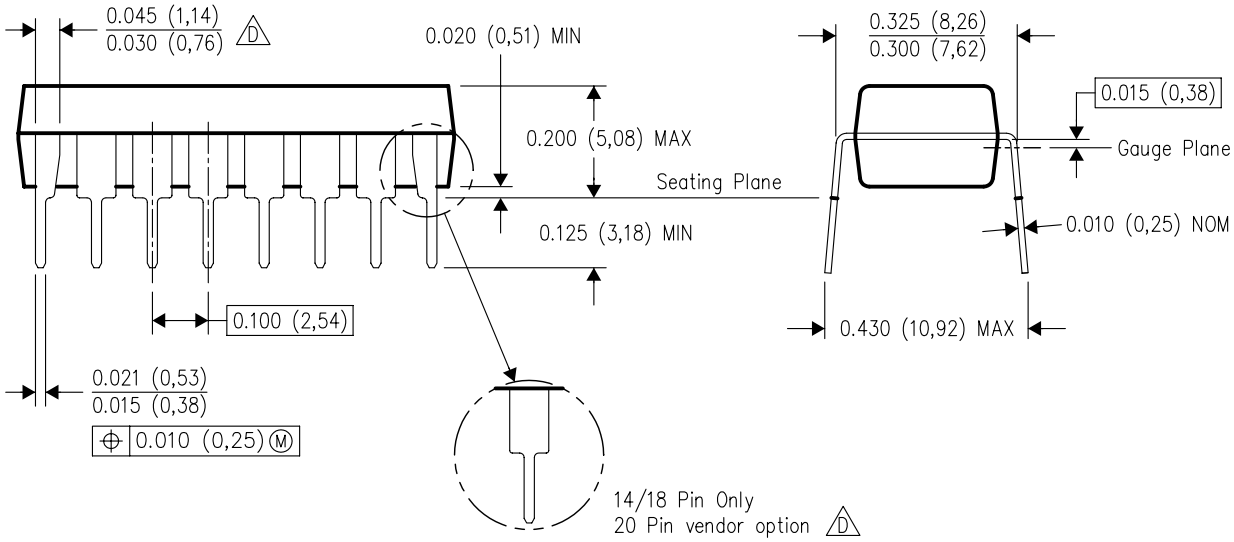
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



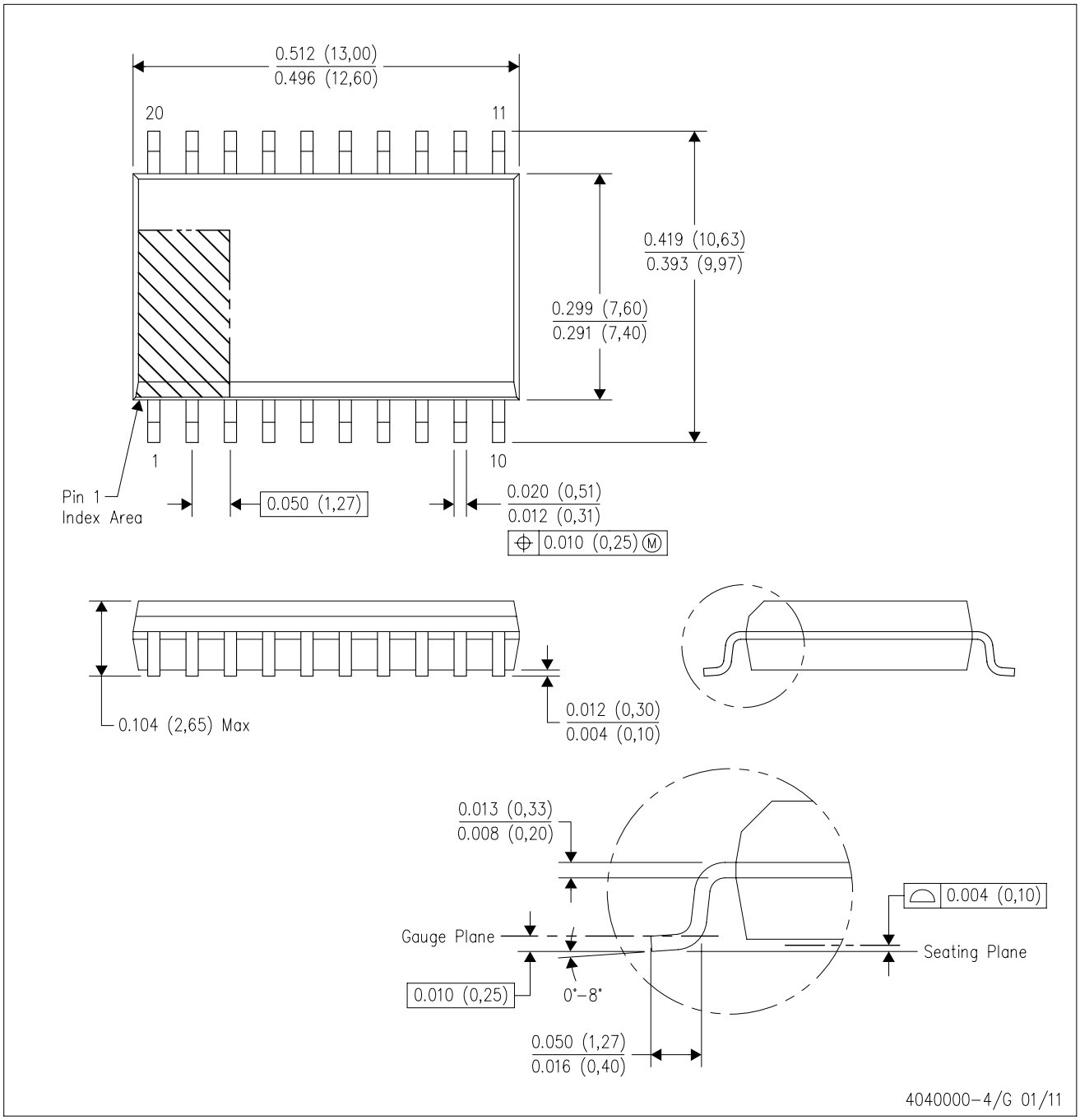
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

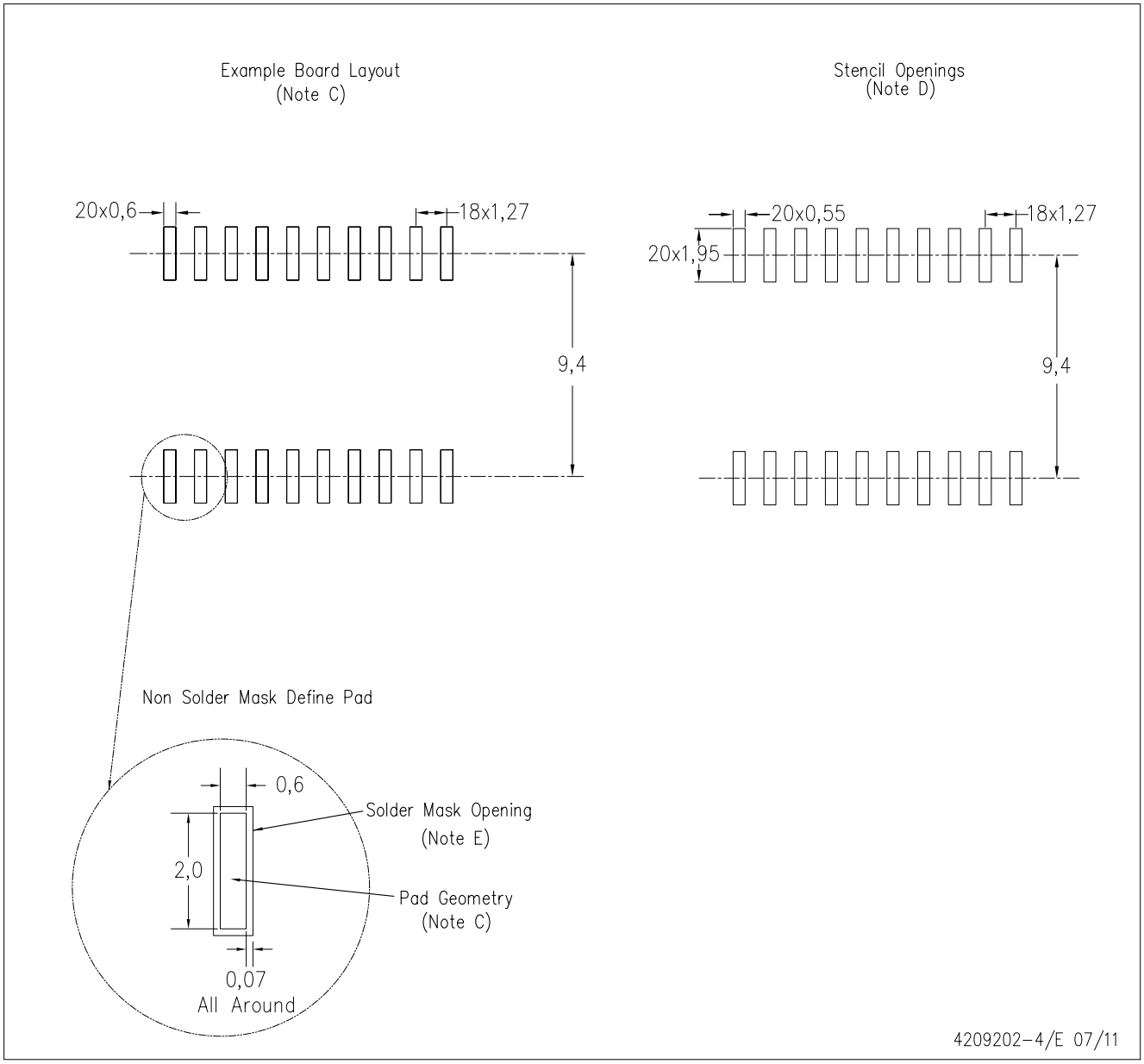
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R–PDSO–G20) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AC.

DW (R–PDSO–G20) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Refer to IPC7351 for alternate board design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265